

ECS
BROKERAGE
EVENT

SME Pitches

PiBond Oy

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PiBond at a glance

- PiBond is a Finnish company with HQ, production and R&D in Finland and supplies materials globally to the industry
- Headcount is ~80 persons, of which 37 are in R&D
- Supplier of lithographic materials used in latest semiconductor process nodes
- Global leader of advanced spin-on dielectrics adopted in sub-3nm semiconductor devices

LITHOGRAPHY

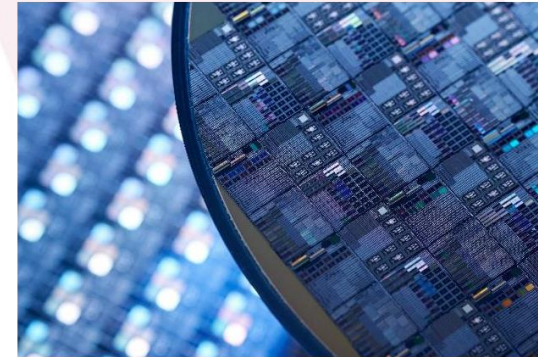
- EUV resist and other specialty resists
- SiBARC – Silicon Middle layer (ML)
- Spin-on Carbon (SOC) and planarizing organic underlayers (UL)

DIELECTRIC

- Global #1 supplier of SOG spin-on glass
- Ultra-low dielectric spin-on dielectrics
- SiO₂-like Photodielectrics

OPTICAL

- Optical coatings with wide RI range (1.2 - 1.9)
- Wafer level optics
- Optical adhesives



Company's Activities

- Collaborative projects
 - Experienced personnel for collaborative projects
 - PiBond has not participated previously in EU's collaborative projects
 - PiBond has received EIC funding
 - Several collaborative projects on National level

Collaboration Expectations

Collaborative projects of interest to you	Chips 2023-CPL-1 & HORIZON-Chips 2024-1-IA-T1
Scope	<p>Provide materials for novel semiconductor devices:</p> <ol style="list-style-type: none"> 1. Inorganic photoresists: silicon and metal-based materials 2. Underlayers: silicon, organic and metal oxide hard masks 3. Novel spin-on low k dielectrics for CVD SiO₂ replacement 4. SiO₂ like photodielectrics and directly patternable hard masks for RDL 5. Optical coatings, bonding adhesives and materials for WLP
Project impact	Strengthen the European semiconductor supply chain with local material supplier & enable the future semiconductor devices with novel material development.
Project consortium	<p>We are searching for partner(s) developing:</p> <ol style="list-style-type: none"> 1. Sub 2nm leading edge system on chip technologies 2. Advanced fully depleted SOI technologies targeting 7nm 3. Advanced packaging and heterogenous integration